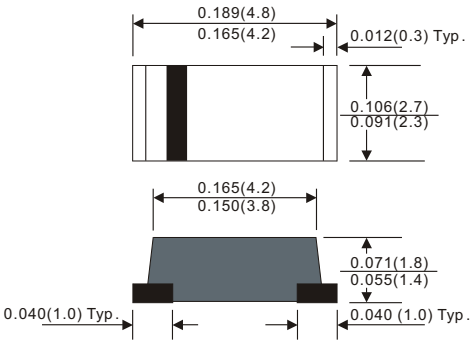
PSL22 thru PSL24

SILICON EPITAXIAL PLANER TYPE

Low VF Chip Schottky Diodes



SMA/DO-214AC



Dimensions in inches and (millimeters)

FEATURES

- Plastic package has Underwriters Laboratory
- Flammability Classification 94V-0 Ufizing Flame
- Retardant Epoxy Molding Compound.
- For surface mounted applications.
- Exceeds environmental standards of ML-S-19500/228
- Low leakage current

MECHANICAL DATA

Case：JEDEC D0-214AC/SMA molded plastic
Terminals：Solder plated, solderable per MIL-STD-750, Method 2026
Polarity：Indicated by cathode band
Mounting Position：Any
Weight：0.05gram

MAXIMUM RATINGS (at T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	Min.	Typ.	Max.	UNITS
Forward rectified current	See Fig.1	I_O			2.0	A
Forward surge current	8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}			50	A
Reverse current	V_R=V_{RRM} T_A=25°C	I_R			1.0	mA
	V_R=V_{RRM} T_A=100°C				10	mA
Thermal resistance	Junction to ambient	R_{JA}		70		°C / W
Diode junction capacitance	F=1MHz and applied 4vDC reverse voltage	C_J		160		pF
Storage temperature		T_{STG}	-55		+150	°C

SYMBOLS	MARKING CODE	V_{RRM} *1 (V)	V_{RMS} *2 (V)	V_R *3 (V)	V_F *4 (V)	Operating Temperature (°C)
PSL22	SL22	20	14	20	0.38	-55 to + 125
PSL23	SL23	30	21	30	0.40	
PSL24	SL24	40	28	40	0.40	

*1 Repetitive peak reverse peak reverse
*2 RMS voltage
*3 Continuous reverse voltage
*4 Maximum forward voltage

PSL22 thru PSL24

SILICON EPITAXIAL PLANER TYPE

Crownpo Technology

FIG.1-TYPICAL FORWARD CHARACTERISTICS

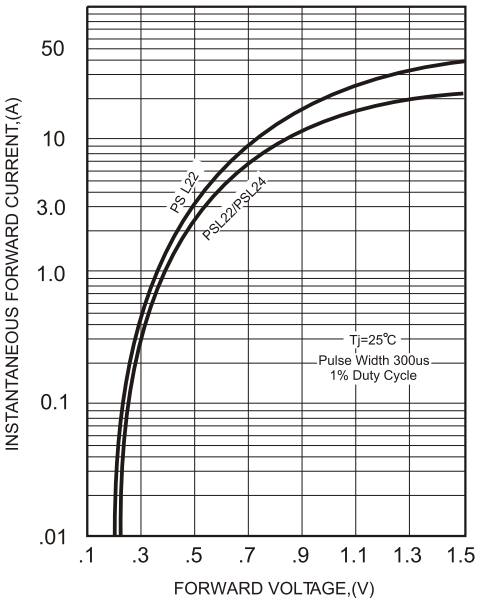


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

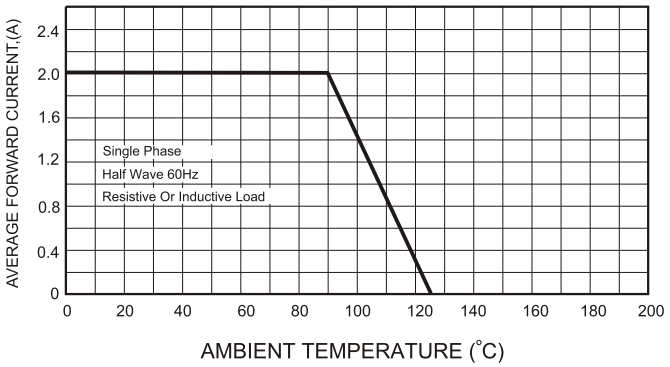


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

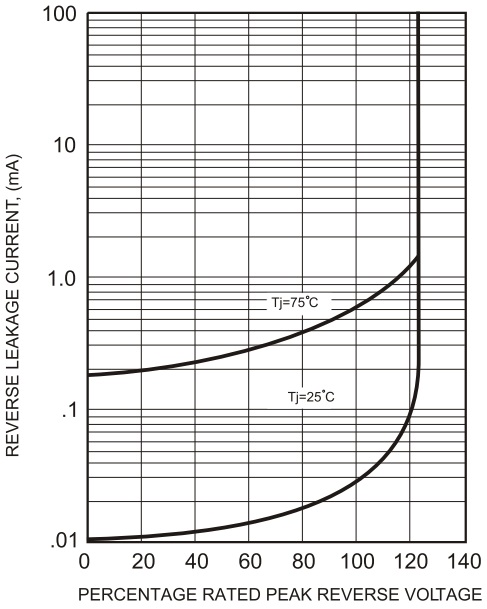


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

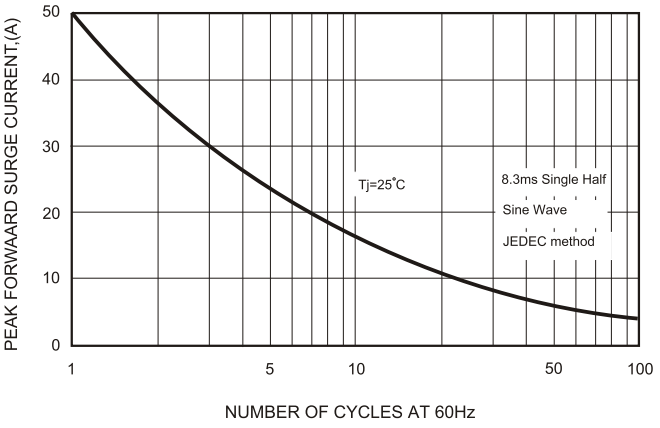


FIG.5-TYPICAL JUNCTION CAPACITANCE

